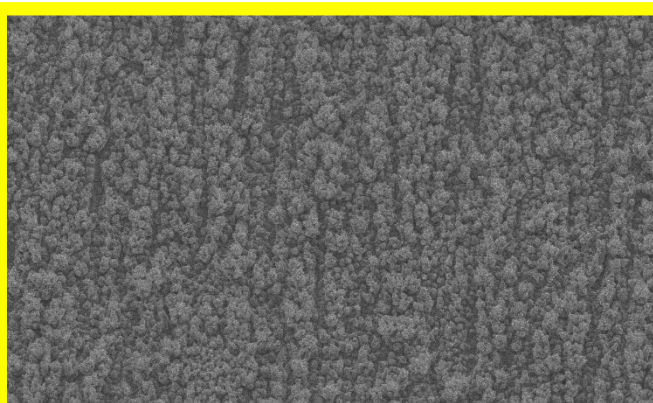
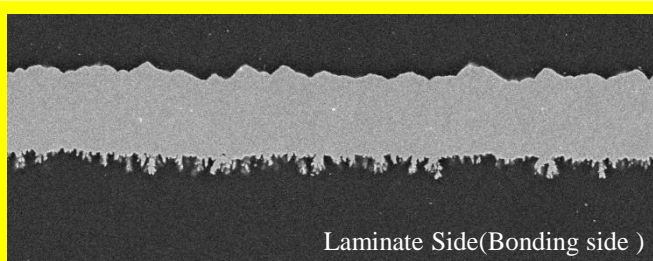


18µm untreated-side Foil SEM × 1,500



18µm treated-side Foil SEM × 1,500

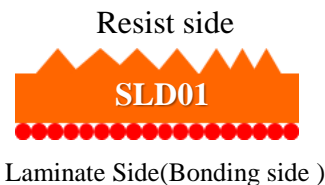


Laminate Side(Bonding side )

18µm Foil Cross Section SEM × 1,000

## Composition :

– Cross Section :



- Resist/ Bonding side Color : Pink/ Pink
- IPC-Grade 3

## Application:

- Outer layer of Server/Switch/Storage
- High speed digital(HSD)
- High Density Interconnector(HDI)
- Material:  
PPO/PPE prepreg/High Tg prepreg  
Mid-Loss/Low-loss/Ultra loss prepreg

## Feature:

- SLD01 foil with very low profile to have excellent signal integrity(SI) performance and high peel strength compared to regular Reverse Treated copper Foil (RTF).
- Special treatment with high peel strength
- low profile of SLD01 makes it an excellent material to apply to high speed transmission board.
- Micro copper-crystal treated, enhance etching ability and anti- undercut ability for fine line process, suitable for HDI board.
- Excellent anti-oxidation and shelf life.

Type	SLD01		Thickness	Physical Properties						Roughness JIS94 (µm)		
				Area Wt.	Tensile(kg/mm2)		Elongation(%)		Peel Strength		Rz (Treated side)	Rz (Untreated side)
	(oz)	(µm)			(µm)	(g/m <sup>2</sup> )	RT	180°C	RT	180°C		
SLD01 (Pink Color)	Toz	12µ	12±1.5	107±5	≥29	≥17	≥3	≥3	≥4.5	≥3.0	≤3.0	≤5.0
	Joz	15µ	15±2.0	125±5	≥29	≥17	≥5	≥4	≥5.0	≥3.5	≤3.0	≤5.5
	Hoz	18µ	18±2.0	153±5	≥29	≥17	≥8	≥4	≥5.5	≥4.5	≤3.0	≤6.0

※ FR4\*1 : Tg ≒ 140°C, LL\*2: Low Loss Resin

※ This is representative data, not guarantee.

*The best application of the copper foil manufacturer & service provider*